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(Unit: mm)

PC813 Series

■ Features

1. High instantaneous common mode rejection voltage

 $(CM_H: TYP.2kV/\mu s)$

- 2. AC input response
- 3. Compact dual-in-line package

PC813 (1ch), PC823 (2ch), PC843 (4ch)

4. High isolation voltage between input and output (V_{iso} : 5 000V $_{rms}$)

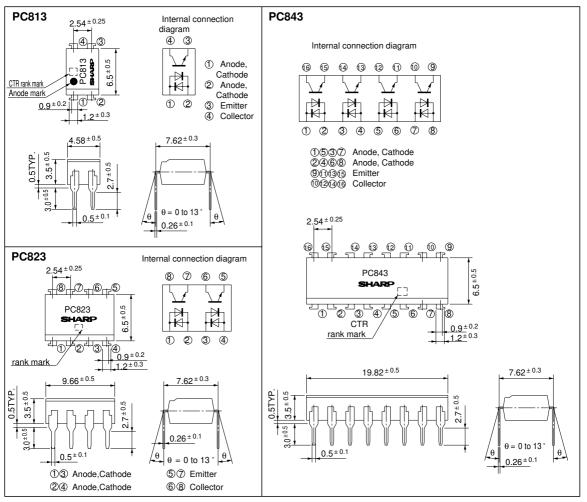
5. Recognized by UL, file No. E64380

AC Input Type & High Noise Reduction Type Photocoupler

■ Applications

- 1. Telephones (**PC813**)
- 2. Programmable controllers
 - (PC823/PC843)
- 3. System appliances, measuring instruments
- Signal transmission between circuits of different potentials and impedances

■ Outline Dimensions



■ Absolute Maximum Ratings

 $(Ta = 25^{\circ}C)$

	Parameter	Symbol	Rating	Unit
Input	Forward current	I_F	± 50	mA
	*1Peak forward current	I_{FM}	± 1	A
	Power dissipation	P	70	mW
Output	Collector-emitter voltage	V _{CEO}	35	V
	Emitter-collector voltage	V ECO	6	V
	Collector current	$I_{\rm C}$	50	mA
	Collector power dissipation	Pc	150	mW
	Total power dissipation	P tot	200	mW
	*2Isolation voltage		5 000	V _{rms}
Operating temperature		T opr	- 30 to + 100	°C
Storage temperature		T stg	- 55 to + 125	°C
	*3Soldering temperature	T sol	260	°C

^{*1} Pulse width \leq =100 μ s, Duty ratio : 0.001

■ Electro-optical Characteristics

 $(Ta = 25^{\circ}C)$

Parameter		Symbol	Conditions	MIN.	TYP.	MAX.	Unit	
Input	Forward voltage		VF	$I_F = \pm 20 \text{mA}$	-	1.2	1.4	V
	Peak forward voltage		V _{FM}	$I_{FM} = \pm 0.5A$	-	-	3.0	V
	Terminal capacitance		Ct	V = 0, $f = 1kHz$	-	50	250	pF
Output	Collector dark current		I _{CEO}	$V_{CE} = 20V, I_{F} = 0$	-	-	10 - 7	A
Transfer charac- teristics	*4Current transfer ratio		CTR	$I_F = \pm 1 \text{mA}, V_{CE} = 5 \text{V}$	20	-	200	%
	Collector-emitter saturation voltage		V _{CE(sat)}	$I_F = \pm 20 \text{mA}, I_C = 1 \text{mA}$	-	0.1	0.2	V
	Isolation voltage		R _{ISO}	DC500V, 40 to 60% RH	5 x 10 ¹⁰	1011	-	Ω
	Floating capacitance		Cf	V = 0, $f = 1MHz$	-	0.6	1.0	pF
	Cut-off frequency		fc	$V_{CE} = 5V$, $I_{C} = 2mA$, $R_{L} = 100 \Omega$, -3dB	15	80	-	kHz
	Response time	Rise time	t _r	$V_{CE} = 2V$, $I_{C} = 2mA$	-	4	18	μs
		Fall time	tf	$R_L = 100 \Omega$	-	5	20	μs
	*5Instantaneous common mode rejection voltage "Output: high level"		СМн	$V_{CM} = 600V, I_F = 0$ $V_O = 2V, R_L = 1.9k\Omega, Vcc=5V$	-	2	-	kV/ μs
	*5Instantaneous common mode rejection voltage "Output: low level"		CM _L	$V_{CM} = 600V, I_F = 16mA$ $V_O = 0.8V, R_L = 1.9k\Omega, Vcc=5V$	-	2	-	kV/ μ s

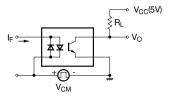
^{*4} Classification table of current transfer ratio is shown below

Model No.	Rank Mark	CTR (%)	
PC813A			
PC823A	A	50 to 150%	
PC843A			
PC813			
PC823	A or no mark	20 to 200%	
PC843			

^{*2 40} to 60% RH, AC for 1 minute

^{*3} For 10 seconds

*5 Test Circuit for instantaneous common mode rejection voltage



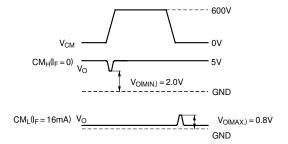


Fig. 1 Forward Current vs. Ambient Temperature

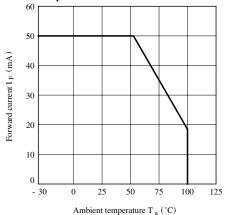


Fig. 3 Peak Forward Current vs. Duty Ratio

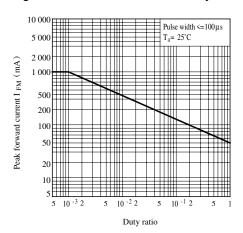


Fig. 2 Collector Power Dissipation vs.
Ambient Temperature

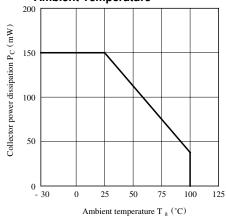


Fig. 4 Forward Current vs. Forward Voltage

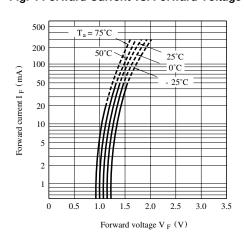


Fig. 5 Current Transfer Ratio vs. Forward Current

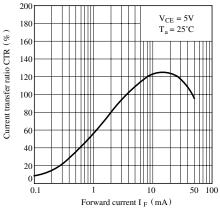


Fig. 7 Relative Current Transfer Ratio vs. Ambient Temperature

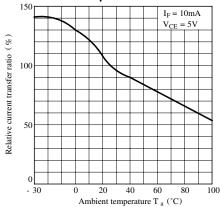


Fig. 9 Collector Dark Current vs.
Ambient Temperature

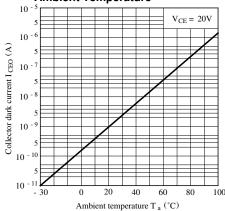


Fig. 6 Collector Current vs.
Collector-emitter Voltage

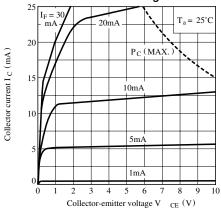


Fig. 8 Collector-emitter Saturation Voltage vs. Ambient Temperature

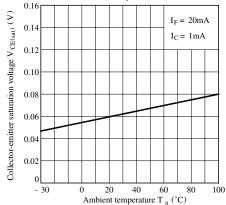


Fig.10 Response Time vs. Load Resistance

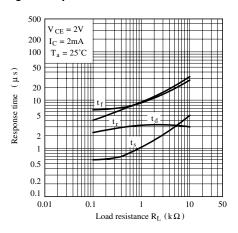


Fig.11 Frequency Response

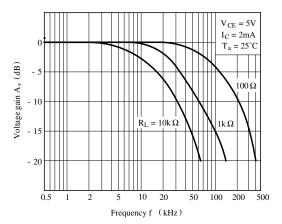
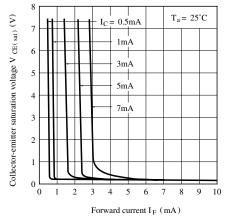
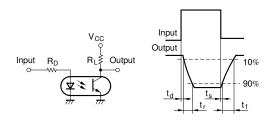


Fig.12 Collector-emitter Saturation Voltage vs. Forward Current

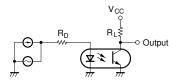


•Please refer to the chapter "Precautions for Use"

Test Circuit for Response Time



Test Circuit for Frepuency Response



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- Various safety devices, etc.
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